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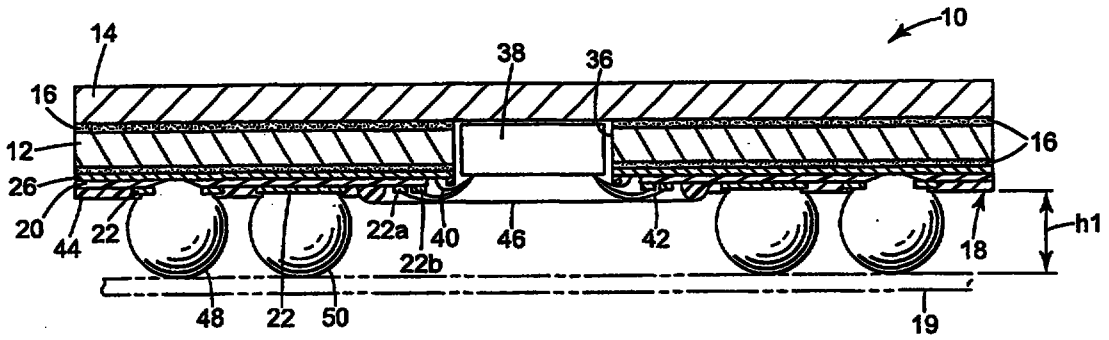
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(54) Title: TAPE BALL GRID ARRAY WITH INTERCONNECTED GROUND PLANE



(57) Abstract

A flexible circuit system includes a flexible dielectric layer having a first conductive layer on a first side and a second conductive layer on a second side. A non–conductive, closed end passage extends through the dielectric layer from the first side to the second side. The first conductive layer is adjacent an open end of the passage at the first side, and the second conductive layer forms the closed end of the passage at the second side. A stiffener member is attached to the second conductive layer. A solder ball is connected to provide a conductive path between the first conductive layer and the second conductive layer.